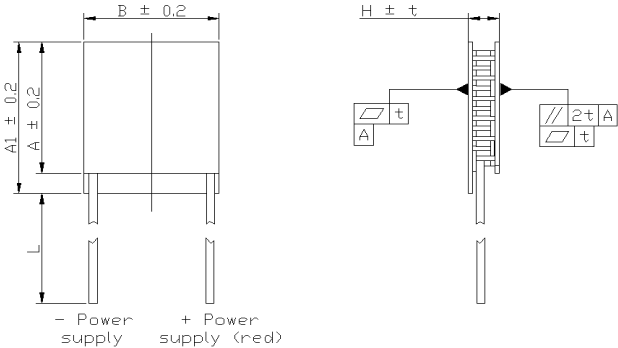


Crystal LTD TM SPEC Form

Thermoelectric module (TM) specification

PO position #	TM	Internal Solder Melting Temp, C	Max operating temperature, °C		Parameters in vacuum at hot side temperature 25 °C				Rac at 25 °C		Ceramic size, mm		TM Height		Wire			Sealing
			short time	continuous operation	I _{max} , A	U _{max} , V	Q _{max} , W	dT _{max} , K	Rac, Ohm	Tolerance ±, %	A/A1	B	Height, mm	Tolerance t, ± mm	S, AWG #	Length, mm	Tolerance ±, mm	
1	S-127-10-08-L2	138	130	115	5.7	16.2	57.6	72.5	2.14	10	30/30	30	3.10	0.02	22 PVC	100	5	
2	C-127-10-08-L2																	
3	H-127-10-08-L2	232	200	150											22 PTFE			
4	CH-127-10-08-L2																	
wire soldered onto external label (tab) for all versions																		

Clamping force: 15.3 - 30.7 kg



Max dT is reduced by 2-3K for silicon sealed and 1-2K for epoxy sealed versions.



U(dT) at Thot=298K

